


 Répondre  Répondre à tous  Transférer    Fermer  Aide

 Vous avez répondu le 01/03/2011 à 15:10.

De: Martine Safon

Date: mar. 01/03/2011 14:34

À: Patrice Delpy

Cc: William Clemens; Alexandre Apcher

Objet : FW: NCP2704 team congratulations - 14 mars

Pièces jointes :

[Afficher sous forme de page Web](#)

Patrice,

Il y a eu un oubli... Désolée...

Souhaites-tu participer à ce repas?

Merci de ton retour

Martine

**From:** Martine Safon

**Sent:** mardi 1 mars 2011 13:59

**To:** Stephane Ramond; William Clemens; Marc Dos Santos; Marc Ryat; Alexandre Apcher; Fabien Foulon; Pascal Tournier; Dominique Romeo; Berengere Le Men; Steve Charpentier; Franck Da Costa; Olivier Martinez; Crystal Zins-Lam; Edmond Gallard; Madeleine Prando; Frederic Garcia; Patrick Aillas; Geraldine Saint Upery; Aude Verges-Copin; Mathieu Gondon

**Subject:** RE: NCP2704 team congratulations - 14 mars

Bonjour,

Au vu du nombre d'absents, William est d'accord pour pousser le repas au lundi 14 mars. Le restaurant est disponible à cette nouvelle date.

Pourriez-vous me confirmer votre disponibilité?

Par avance merci

Martine

**From:** William Clemens

**Sent:** vendredi 25 février 2011 19:15

**To:** Marc Dos Santos; Marc Ryat; Stephane Ramond; Alexandre Apcher; Fabien Foulon; Pascal Tournier; Dominique Romeo; Berengere Le Men; Steve Charpentier; Franck Da Costa; Olivier Martinez; Crystal Zins-Lam; Edmond Gallard; Madeleine Prando; Frederic Garcia; Patrick Aillas; Geraldine Saint Upery; Aude Verges-Copin; Mathieu Gondon

**Cc:** Martine Safon

**Subject:** NCP2704 team congratulations

**Bonjour à toutes et à tous, (en espérant n'avoir oublié personne...)**

**Voilà un an et demi (déjà) nous démarrions le NCP2704 qui, grâce aux efforts fournis par toute l'équipe tout au long des différentes étapes, a été introduit sur le marché en fin d'année dernière avec des commandes à la clé et de belles perspectives d'opportunités à venir.**

**Afin de célébrer l'aboutissement de cette belle collaboration et aussi je l'espère vraiment le début d'une véritable réussite commerciale, je vous propose de nous réunir autour d'un bon festin à « La brasserie du Stade », à l'image de l'équipe J.**

**La date proposée est le 7 Mars à Midi.**

**Merci de confirmer, par retour d'email, en début de semaine prochaine votre présence.**

**Martine,**

**N'étant pas là la semaine prochaine, pourrais-tu s'il te plait réserver une table à « La brasserie du stade » pour une 20aine de personnes (une bonne équipe de rugby...) – Nous serons ravis de te compter parmi nous J**

**Merci à tous**

**A+**

**Will**

William CLEMENS

LVPM - Project Manager

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**ON Semiconductor**

132, chemin de Basso Cambo - BP 53512


31035 Toulouse Cedex 1

Tél: (+33) 0 534 61 10 00

Fax: (+33) 0 534 61 10 50

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 Vous avez répondu le 21/03/2011 à 10:01.

De: William Clemens Date: ven. 18/03/2011 15:23  
À: Dominique Omet; Pierre Genest; Bernard Remaury; Crystal Zins-Lam; Patrice Delpy; Edmond Gallard; Madeleine Prando; Erdogan Delipinar; Patrick Gueulle; Remi Gerber; Maxime Lybliamay; Alexandre Apcher; Geraldine Saint Upery; Aude Verges-Copin; Christel Moreau  
Cc: Martine Safon  
Objet : NCP367 team congratulations  
Pièces jointes :

[Afficher sous forme de page Web](#)

Bonjour à toutes et à tous,

Comme vous le savez sûrement déjà plusieurs versions du NCP367 sont sur le marché et génèrent des revenus. Deux versions ont été qualifiées fin 2010 pour Samsung et 2 autres versions ont suivi le pas en tout début d'année pour une nouvelle opportunité chez Alpha.

Après quelques forts rebondissements, un faux départ, un passage de témoin mal synchronisé, une petite frayeur technique et un partage de ressources difficile, c'est grâce aux efforts de toute l'équipe que cette aventure c'est finalement transformée en succès.

Afin de fêter comme il se doit cet aboutissement et les efforts de chacun, je vous propose de nous réunir autour d'un bon repas le Mardi 29 Mars à la brasserie du stade au sept deniers.

Afin de prévoir le nombre de personnes et de confirmer la réservation au plus tôt, merci de confirmer votre présence auprès de Martine.

Merci à tous

A+

Will

William CLEMENS

LVPM - Project Manager

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**ON Semiconductor**

132, chemin de Basso Cambo - BP 53512

31035 Toulouse Cedex 1

Tél: (+33) 0 534 61 10 00

Fax: (+33) 0 534 61 10 50

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 Répondre  Répondre à tous  Transférer    Fermer  Aide

De: William Clemens  
À: Berengere Le Men; Alexandre Apcher; Virginie Duchemann; Fabien Foulon; Patrice Delpy  
Cc:  
Objet : RE: first evaluation results of the NCS8381  
Pièces jointes :

Date: ven. 08/07/2011 15:20

[Afficher sous forme de page Web](#)

Tout est dit ... Excellent !! Le weekend s'annonce bien J

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**William Clemens | Project Manager**

**ON Semiconductor France SA | 132, chemin de Basso Cambo - BP 53512 | 31035 Toulouse Cedex 1 | France**  
(: +33 534 61 1238 - )6: +33 534 61 1050 - \*: [william.clemens@onsemi.com](mailto:william.clemens@onsemi.com)

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**From:** Berengere Le Men  
**Sent:** Friday, July 08, 2011 2:44 PM  
**To:** Alexandre Apcher; Virginie Duchemann; Fabien Foulon; William Clemens; Patrice Delpy  
**Subject:** FW: first evaluation results of the NCS8381

Pour le plaisir J

**From:** Eric Joseph  
**Sent:** Thursday, July 07, 2011 7:21 PM  
**To:** Berengere Le Men  
**Cc:** Bertrand Clou  
**Subject:** RE: first evaluation results of the NCS8381

Great job Berengere. Please pass on my congratulations to the team.

Eric Joseph

VP, Design Engineering, CCPG

ON Semiconductor

1-602-244-5414

1-602-451-6110

**From:** Berengere Le Men

**Sent:** Wednesday, July 06, 2011 7:59 AM

**To:** Thibault Kassir; Eric Joseph

**Cc:** Stephen Dow; Radhika Venkatasubramanian; Adrian Lin; Brian Ballweber; David Lovelace; Martin Kejhar; Ling-Miao Chou; Josh Warner; Darren Hooks; Lang Dinh; Bob Boos; David McDonald; Bertrand Clou; Tim Gurnett; Philippe Andre; Dominique Romeo

**Subject:** first evaluation results of the NCS8381

Hello Thibault and Eric,

We just received the NCS8381 samples and we would like to share with you good news.

Indeed the preliminary evaluation shows good operating of the device. We did some audio listening of the amplifier in different modes and different power supplies with good responses at low and high power (full scale range) and in stereo. We did also some preliminary measurements on a first circuit with THD results in line with what expected (0.02% at 1kHz 8W 8Ohms and 16V). Noise measurements show results for now a little higher than expected (SNR=97dB instead of 100dB) but it's still very preliminary and investigation is ongoing. We tested also quickly functions like volume control, balance left and right, anti-clipping and DRC functions with good results. We tested different sample rates and different configurations which look ok.

The first results validate that the following blocks are functional:

- I2C/I2S interfaces
- Power tree (bias, 1.875V regulator and low noise buffer)
- 400MHz PLL
- Digital Signal Processing: Interpolation filters, PCM-PWM Modulator
- Digital audio enhancement: DRC, PGA, Balance, anti-clip
- PWM analog amplifier

These results are preliminary and need of course to be refined: the evaluation is pursuing. We keep you

posted.

If you want to enjoy the real life demo (audio), we will make it available soon under sharepoint project folder.

Best regards,

Berengere LE MEN, Philippe ANDRE, Dominique ROMEO

 Répondre  Répondre à tous  Transférer    Fermer  Aide

De: Eric Joseph Date: mer. 20/04/2011 22:07  
Bertrand Clou; Alexandre Apcher; Berengere Le Men; Geraldine Saint Upery;  
Hassan Chaoui; Stephanie Cambounet; Anissa Karray-Kbaier; Aurore Masson;  
À: Fabien Foulon; Julien Clemens; Patrice Delpy; Virginie Duchemann; Christophe  
Pinatel; Dominique Romeo; Marc Dos Santos; Marc Ryat; Pascal Tournier;  
Stephane Colomines; Stephane Ramond; Steve Charpentier  
Tim Gurnett; Brian Pickard; Darren Hooks; Monica Griffin; Stephen Dow; Martin  
Cc: Kejhar; Jozef Kiss; Milan Valenta; Philippe Andre; Bob Boos; Lang Dinh; Renato  
Golecruz; Josh Warner; David McDonald; Thibault Kassir; Simon Keeton  
Objet : RE: NCS8381 Tape out done on time! :-)  
Pièces jointes :

[Afficher sous forme de page Web](#)

Outstanding job. Thanks.

-----Original Message-----

From: Bertrand Clou

Sent: Wednesday, April 20, 2011 10:13 AM

To: Alexandre Apcher; Berengere Le Men; Geraldine Saint Upery; Hassan Chaoui; Stephanie Cambounet; Anissa Karray-Kbaier; Aurore Masson; Fabien Foulon; Julien Clemens; Patrice Delpy; Virginie Duchemann; Christophe Pinatel; Dominique Romeo; Marc Dos Santos; Marc Ryat; Pascal Tournier; Stephane Colomines; Stephane Ramond; Steve Charpentier

Cc: Tim Gurnett; Brian Pickard; Darren Hooks; Monica Griffin; Stephen Dow; Martin Kejhar; Jozef Kiss; Milan Valenta; Philippe Andre; Bob Boos; Lang Dinh; Renato Golecruz; Josh Warner; David McDonald; Thibault Kassir; Eric Joseph; Simon Keeton

Subject: NCS8381 Tape out done on time! :-)

Importance: High

All,

For your information, Dominique and Alexandre have just sent the gds of the reticule that contains the 8381

Congratulations to the audio team (Tlse and Austin), verification and Physical design teams (Tlse and Roznov) for their hard work to meet this key milestone for the NCS8381 project.

Thank you also to the rest of project team for their collaboration and support.

Regards,

Berengere & Bertrand

-----Original Message-----

From: Alexandre Apcher

Sent: Wednesday, April 20, 2011 6:27 PM

To: Berengere Le Men; 'zrhuang@tsmc.com'; Toby@ememory.com.tw

Cc: Tim Gurnett; Chris Gibson; 'EHAAS@tsmc.com'; 'GTHALLIKAR@tsmc.com'; 'JXYHUANG@tsmc.com'; 'LZENG@tsmc.com'; 'RWATERS@tsmc.com'; 'HHFAN@tsmc.com'; 'ALEEA@tsmc.com'; 'ems\_manager@tsmc.com'; Dominique Romeo; Darren Hooks; Bertrand Clou

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64\_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Hello Zi-Ran, Hello Toby,

We have just submit the gds and the tape out form for the reticule TMEL64\_C22 on the 27th april cybershuttle.

Find attached the die saw diagram updated.

Toby,

Find in attachment the IP merge forms fully completed.

As we use EO01x32KCT1 we don't fill the items 10 in IP Merge Notice request Form 2011. Please confirm that it s OK If you

encounter any trouble or if you have any questions, Please do not hesitate to contact: Tim gurnett, berengere Lemen, bertrand clou, alexandre apcher, dominique romeo (ONSEMI guys in copy of this mail).

Additional informations for the IP merge:

There are 4 dies on the reticule. Only 2 contains OTP eMemory IP.

Best Regards,  
Alexandre Apcher

-----Original Message-----

From: Berengere Le Men

Sent: Monday, April 18, 2011 11:19 AM

To: zrhuang@tsmc.com

Cc: Tim Gurnett; Chris Gibson; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com;

LZENGGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems\_manager@tsmc.com; Alexandre Apcher; Dominique Romeo; Darren Hooks

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64\_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Hello Zi-Ran,

We'll send it to you as soon as it's ready.

Best regards,  
Berengere.

-----Original Message-----

From: zrhuang@tsmc.com [<mailto:zrhuang@tsmc.com>]

Sent: Monday, April 18, 2011 11:15 AM

To: Berengere Le Men

Cc: Tim Gurnett; Chris Gibson; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com;

LZENGGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems\_manager@tsmc.com; Alexandre Apcher; Dominique Romeo; Darren Hooks; zrhuang@tsmc.com

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64\_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Dear Berengere,

Many thanks for your info.

Could you please provide the floor plan to me for extra die-saw availability checking since you require that ?

Thanks again ~

Below mail mentioned:

If your tape-out contains multiple designs and needs TSMC to do extra die-saw in order to singulate each sub-chip, please email the die-saw floor plan to me by 04/20/2011.

Thanks and best regards!

-----  
Zi-Ran (Nature) Huang 黃自然

CyberShuttle Service

Taiwan Semiconductor Manufacturing Company, Ltd.

No.121, Park Ave.3, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C

Tel: 886-3-5636688

Ext: 702-2199

zrhuang@tsmc.com

"Berengere Le

Men" To: <ZRHUANG@tsmc.com>

<Berengere.LeMen@ onsemi.com> cc: "Tim Gurnett" <Tim.Gurnett@onsemi.com>, "Chris Gibson"

<GTHALLIKAR@tsmc.com>, <Chris.Gibson@onsemi.com>, <EHAAS@tsmc.com>,

<JXYHUANG@tsmc.com>, <LZENGA@tsmc.com>, <RWATERS@tsmc.com>,  
<HHFAN@tsmc.com>,

2011/04/18 05:07 <ALEEA@tsmc.com>, <ems\_manager@tsmc.com>, "Alexandre  
Apcher"

PM <Alexandre.Apcher@onsemi.com>, "Dominique Romeo"  
<dominique.romeo@onsemi.com>,

"Darren Hooks" <Darren.Hooks@onsemi.com>

CyberShuttle Subject: RE: SECURITY C - ON [0.18 UM, TMEL64\_C22, 04/27/2011]: Request

PO/Tape-out Form/GDS File

Hello Zi-Ran,

I would like to inform you that we will tape-out a reticule with 4 dies in total: 2 dies of 2160.0 um x 4160.0 um each, and 2 other dies of 1750um x 400um each.

Best regards,  
Berengere.

-----Original Message-----

From: ZRHUANG@tsmc.com [<mailto:ZRHUANG@tsmc.com>]

Sent: Wednesday, April 13, 2011 9:55 AM

To: Darren Hooks

Cc: Tim Gurnett; Berengere Le Men; Chris Gibson; ZRHUANG@tsmc.com; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com; LZENGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems\_manager@tsmc.com

Subject: SECURITY C - ON [0.18 UM, TMEL64\_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Dear Darren Hooks

TMEL64 CyberShuttle is about to be launched. (Shuttle type: 0.18 UM CMOS High Voltage Mixed Signal based General Purpose BCD Dual Gate FSG AL 1P6M 1.8/5/18/24/32/40V Vg1.8/5V). Please use TMEL64\_C22 as the TSMC Product Name for your device.

If your tape-out contains multiple designs and needs TSMC to do extra die-saw in order to singulate each sub-chip, please

email the die-saw floor plan to me by 04/20/2011.

By 04/27/2011 10:00AM Taiwan time (GMT +8), I need the following tape-in materials.

1. PO & Prepayment: Please send it to TSMC (ALEEA@tsmc.com) 2. GDS2

Database: Please put it under one of our FTP servers (e.g. ftp.tsmc.com.tw).

3. Tape-Out Form: Please fill out the form on TSMC-Online, submit it, and pass "DB Check". (To fill out the form, please access TSMC-Online > Business Transactions > CyberShuttle > Online Tape-Out Form > Create Tape-Out Form. After submitting the form, an auto DB Check program will check whether the Tape-Out Form complies with the GDS database, and email you the checking results shortly.

If your device needs TSMC to merge IP/library, please contact your account manager(EHAAS@tsmc.com, GTHALLIKAR@tsmc.com, JXYHUANG@tsmc.com, LZENGA@tsmc.com, RWATERS@tsmc.com) or customer service

manager(HHFAN@tsmc.com) in advance and send your GDS file to TSMC no later than 04/21/2011. Please remember to put the IP merged GDS file, but not the GDS before IP merge, on the tape-out form.

TSMC Product Name: TMEL64\_C22

\*\* Customer Tape-Out Information \*\* (Status : approved)

- 
1. Resv No: 227437
  2. Tape-in Date: 04/27/2011
  3. Fab: FAB8B
  4. Geometry: 0.18 UM
  5. TM Number: TMEL64
  6. Shuttle Type: 0.18 UM CMOS High Voltage Mixed Signal based General Purpose BCD Dual Gate FSG AL 1P6M 1.8/5/18/24/32/40V Vg1.8/5V 7.

Customer Product Name: NCS8381 8. For which application is your design primarily intended? Consumer--Digital TV/HDTV 9. How many devices are included in this tape-out? 1 10. What do you use CyberShuttle for?

(Check all that apply) circuit characterizaion, IP verification, full chip verification, engineering samples 11. Is this tape-out a new design or a re-design? new design Please specify its previous device name:

12. When will be your follow-up new product at TSMC based on this shuttle verification result? 201109 13. #P#M: 1P6M 14. Chip Size: X = 2160.0 um, Y = 4100.0 um, Shrinkage = 100%, Blocks = 1.0

15. Bumping: No (Bumping needs NRE surcharge.)

16. RDL: No (RDL, redistribution layers for bumping process, needs NRE surcharge.)

17. Extra Die-Saw: Yes

18. Sample Quantity: Bare Dice 360 + Packaged Chips 0, Package Type: NONE

Extra Sub-chips: 0 Whole Sample Wafers: Yes, 1 piece(s) Extra Charged Wafers: 9 piece(s) 19. Split Condition: No 20. Need TSMC IP

Merge: Yes 21. Special Requests:

OTP None

22. Remarks: 1) Require MIM caps, HRI poly, UTM and OTP options.

2) Back grind wafers / die to 11 mils thickness

3) Full processing of first sawn 40 pc block + three wafers.

4) Hold remaining five wafers at pre-metal (prior to metal processing) in anticipation of future metal design modifications.

5) Request overnight shipment to: Mr. Tim Gurnett (602-244-4181); SCI LLC, 5005 E McDowell Rd, M/D E6100, Phoenix, Arizona, 85008, United States 23. Company Code: U797 24. Company Name: ON 25. Contact Person:

Darren Hooks 26. Email: darren.hooks@onsemi.com 27. TEL No: 602 244 6468 28. Email Cc:

tim.gurnett@onsemi.com,berengere.lemen@onsemi.com,chris.gibson@onsemi.com

m

29. Account Manager Email: EHAAS@tsmc.com, GTHALLIKAR@tsmc.com, JXYHUANG@tsmc.com,

LZENGA@tsmc.com, RWATERS@tsmc.com 30. Customer Support Email: ALEEA@tsmc.com 31. Customer Service Manager Email:

HHFAN@tsmc.com 32. CyberShuttle Captain Email: ZRHUANG [ZRHUANG@tsmc.com] 33. TSMC Remarks:  
-----

IP Clarification: Please perform IP Clarification on TSMC-Online to prevent from using Problematic IP/Lib. (To perform IP Clarification, please access TSMC-Online > TapeOut & Mask Service > IP Clarification and follow the steps. After submitting the form, the IP Clarification report will be sent by email in 30 minutes. )

Sincerely yours,

TSMC CyberShuttle Team  
Zi-Ran Huang

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 Répondre
  Répondre à tous
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**De:** Thibault Kassir **Date:** mer. 20/04/2011 19:23  
 Bertrand Clou; Alexandre Apcher; Berengere Le Men; Geraldine Saint Upery;  
 Hassan Chaoui; Stephanie Cambounet; Anissa Karray-Kbaier; Aurore Masson;  
**À:** Fabien Foulon; Julien Clemens; Patrice Delpy; Virginie Duchemann; Christophe  
 Pinatel; Dominique Romeo; Marc Dos Santos; Marc Ryat; Pascal Tournier;  
 Stephane Colomines; Stephane Ramond; Steve Charpentier  
 Tim Gurnett; Brian Pickard; Darren Hooks; Monica Griffin; Stephen Dow; Martin  
**Cc:** Kejhar; Jozef Kiss; Milan Valenta; Philippe Andre; Bob Boos; Lang Dinh; Renato  
 Golecruz; Josh Warner; David McDonald; Eric Joseph; Simon Keeton  
**Objet :** RE: NCS8381 Tape out done on time! :-)  
**Pièces jointes :**

[Afficher sous forme de page Web](#)

Bertrand and design teams,

This is a critical milestone and a major step forward in our engagement in LCD TV Audio. I want to thank you all for your hard work and efforts in making this milestone a reality. We look forward to having samples!

Sincere thank you to the entire project team.

Best Regards,  
Thibault

-----Original Message-----

From: Bertrand Clou

Sent: Wednesday, April 20, 2011 10:13 AM

To: Alexandre Apcher; Berengere Le Men; Geraldine Saint Upery; Hassan Chaoui; Stephanie Cambounet; Anissa Karray-Kbaier; Aurore Masson; Fabien Foulon; Julien Clemens; Patrice Delpy; Virginie Duchemann; Christophe Pinatel; Dominique Romeo; Marc Dos Santos; Marc Ryat; Pascal Tournier; Stephane Colomines; Stephane Ramond; Steve Charpentier

Cc: Tim Gurnett; Brian Pickard; Darren Hooks; Monica Griffin; Stephen Dow; Martin Kejhar; Jozef Kiss; Milan Valenta; Philippe Andre; Bob Boos; Lang Dinh; Renato Golecruz; Josh Warner; David McDonald; Thibault Kassir; Eric Joseph; Simon Keeton

Subject: NCS8381 Tape out done on time! :-)

Importance: High

All,

For your information, Dominique and Alexandre have just sent the gds of the reticule that contains the 8381

Congratulations to the audio team (Tlse and Austin), verification and Physical design teams (Tlse and Roznov) for their hard work to meet this key milestone for the NCS8381 project.

Thank you also to the rest of project team for their collaboration and support.

Regards,  
Berengere & Bertrand

-----Original Message-----

From: Alexandre Apcher

Sent: Wednesday, April 20, 2011 6:27 PM

To: Berengere Le Men; 'zrhuang@tsmc.com'; Toby@ememory.com.tw

Cc: Tim Gurnett; Chris Gibson; 'EHAAS@tsmc.com'; 'GTHALLIKAR@tsmc.com'; 'JXYHUANG@tsmc.com'; 'LZENGA@tsmc.com'; 'RWATERS@tsmc.com'; 'HHFAN@tsmc.com'; 'ALEEA@tsmc.com'; 'ems\_manager@tsmc.com'; Dominique Romeo; Darren Hooks; Bertrand Clou

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64\_C22,04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Hello Zi-Ran, Hello Toby,

We have just submit the gds and the tape out form for the reticule TMEL64\_C22 on the 27th april cybershuttle.  
Find attached the die saw diagram updated.

Tobby,

Find in attachment the IP merge forms fully completed.

As we use EO01x32KCT1 we don't fill the items 10 in IP Merge Notice request Form 2011. Please confirm that it s OK If you encounter any trouble or if you have any questions, Please do not hesitate to contact: Tim gurnett, berengere Lemen, bertrand clou, alexandre apcher, dominique romeo (ONSEMI guys in copy of this mail).

Additional informations for the IP merge:

There are 4 dies on the reticule. Only 2 contains OTP eMemory IP.

Best Regards,  
Alexandre Apcher

-----Original Message-----

From: Berengere Le Men

Sent: Monday, April 18, 2011 11:19 AM

To: zrhuang@tsmc.com

Cc: Tim Gurnett; Chris Gibson; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com; LZENGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems\_manager@tsmc.com; Alexandre Apcher; Dominique Romeo; Darren Hooks

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64\_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Hello Zi-Ran,

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Best regards,  
Berengere.

-----Original Message-----

From: zrhuang@tsmc.com [<mailto:zrhuang@tsmc.com>]

Sent: Monday, April 18, 2011 11:15 AM

To: Berengere Le Men

Cc: Tim Gurnett; Chris Gibson; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com; LZENGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems\_manager@tsmc.com; Alexandre Apcher; Dominique Romeo; Darren Hooks; zrhuang@tsmc.com

Subject: RE: SECURITY C - ON [0.18 UM, TMEL64\_C22, 04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Dear Berengere,

Many thanks for your info.

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Thanks again ~

Below mail mentioned:

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Thanks and best regards!

-----  
Zi-Ran (Nature) Huang 黃自然  
CyberShuttle Service  
Taiwan Semiconductor Manufacturing Company, Ltd.

No.121,Park Ave.3, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C  
Tel: 886-3-5636688  
Ext: 702-2199  
zrhuang@tsmc.com

"Berengere Le

Men" To: <ZRHUANG@tsmc.com>

<Berengere.LeMen@ onsemi.com> cc: "Tim Gurnett" <Tim.Gurnett@onsemi.com>, "Chris Gibson"

<GTHALLIKAR@tsmc.com>, <Chris.Gibson@onsemi.com>, <EHAAS@tsmc.com>,

<JXYHUANG@tsmc.com>, <LZENGA@tsmc.com>, <RWATERS@tsmc.com>,  
<HHFAN@tsmc.com>,

2011/04/18 05:07 <ALEEA@tsmc.com>, <ems\_manager@tsmc.com>, "Alexandre  
Apcher"

PM <Alexandre.Apcher@onsemi.com>, "Dominique Romeo"  
<dominique.romeo@onsemi.com>,

"Darren Hooks" <Darren.Hooks@onsemi.com>

CyberShuttle Subject: RE: SECURITY C - ON [0.18 UM, TMEL64\_C22,04/27/2011]: Request

PO/Tape-out Form/GDS File

Hello Zi-Ran,

I would like to inform you that we will tape-out a reticule with 4 dies in total: 2 dies of 2160.0 um x 4160.0 um each, and 2 other dies of 1750um x 400um each.

Best regards,  
Berengere.

-----Original Message-----

From: ZRHUANG@tsmc.com [<mailto:ZRHUANG@tsmc.com>]

Sent: Wednesday, April 13, 2011 9:55 AM

To: Darren Hooks

Cc: Tim Gurnett; Berengere Le Men; Chris Gibson; ZRHUANG@tsmc.com; EHAAS@tsmc.com; GTHALLIKAR@tsmc.com; JXYHUANG@tsmc.com; LZENGA@tsmc.com; RWATERS@tsmc.com; HHFAN@tsmc.com; ALEEA@tsmc.com; ems\_manager@tsmc.com

Subject: SECURITY C - ON [0.18 UM, TMEL64\_C22,04/27/2011]: Request CyberShuttle PO/Tape-out Form/GDS File

Dear Darren Hooks

TMEL64 CyberShuttle is about to be launched. (Shuttle type: 0.18 UM CMOS High Voltage Mixed Signal based General Purpose BCD Dual Gate FSG AL 1P6M 1.8/5/18/24/32/40V Vg1.8/5V). Please use TMEL64\_C22 as the TSMC Product Name for your device.

If your tape-out contains multiple designs and needs TSMC to do extra die-saw in order to singulate each sub-chip, please email the die-saw floor plan to me by 04/20/2011.

By 04/27/2011 10:00AM Taiwan time (GMT +8), I need the following tape-in materials.

1. PO & Prepayment: Please send it to TSMC (ALEEA@tsmc.com) 2. GDS2

Database: Please put it under one of our FTP servers (e.g. ftp.tsmc.com.tw).

3. Tape-Out Form: Please fill out the form on TSMC-Online, submit it, and pass "DB Check". (To fill out the form, please access TSMC-Online > Business Transactions > CyberShuttle > Online Tape-Out Form > Create Tape-Out Form. After submitting the form, an auto DB Check program will check whether the Tape-Out Form complies with the GDS database, and email you the checking results shortly.

If your device needs TSMC to merge IP/library, please contact your account manager(EHAAS@tsmc.com, GTHALLIKAR@tsmc.com, JXYHUANG@tsmc.com, LZENGA@tsmc.com, RWATERS@tsmc.com) or customer service

manager(HHFAN@tsmc.com) in advance and send your GDS file to TSMC no later than 04/21/2011. Please remember to put the IP merged GDS file, but not the GDS before IP merge, on the tape-out form.

TSMC Product Name: TMEL64\_C22

\*\* Customer Tape-Out Information \*\* (Status : approved)

- 
1. Resv No: 227437
  2. Tape-in Date: 04/27/2011
  3. Fab: FAB8B
  4. Geometry: 0.18 UM
  5. TM Number: TMEL64
  6. Shuttle Type: 0.18 UM CMOS High Voltage Mixed Signal based General Purpose BCD Dual Gate FSG AL 1P6M 1.8/5/18/24/32/40V Vg1.8/5V 7.

Customer Product Name: NCS8381 8. For which application is your design primarily intended? Consumer--Digital TV/HDTV 9. How many devices are included in this tape-out? 1 10. What do you use CyberShuttle for?

(Check all that apply) circuit characterizaion, IP verification, full chip verification, engineering samples 11. Is this tape-out a new design or a re-design? new design Please specify its previous device name:

12. When will be your follow-up new product at TSMC based on this shuttle verification result? 201109 13. #P#M: 1P6M 14. Chip Size: X = 2160.0 um, Y = 4100.0 um, Shrinkage = 100%, Blocks = 1.0

15. Bumping: No (Bumping needs NRE surcharge.)

16. RDL: No (RDL, redistribution layers for bumping process, needs NRE surcharge.)

17. Extra Die-Saw: Yes

18. Sample Quantity: Bare Dice 360 + Packaged Chips 0, Package Type: NONE

Extra Sub-chips: 0 Whole Sample Wafers: Yes, 1 piece(s) Extra Charged Wafers: 9 piece(s) 19. Split Condition: No 20. Need TSMC IP

Merge: Yes 21. Special Requests:

OTP None

22. Remarks: 1) Require MIM caps, HRI poly, UTM and OTP options.

2) Back grind wafers / die to 11 mils thickness

3) Full processing of first sawn 40 pc block + three wafers.

4) Hold remaining five wafers at pre-metal (prior to metal processing) in anticipation of future metal design modifications.

5) Request overnight shipment to: Mr. Tim Gurnett (602-244-4181); SCI LLC, 5005 E McDowell Rd, M/D E6100, Phoenix,

Arizona, 85008, United States 23. Company Code: U797 24. Company Name: ON 25. Contact Person:

Darren Hooks 26. Email: darren.hooks@onsemi.com 27. TEL No: 602 244 6468 28. Email Cc:  
tim.gurnett@onsemi.com,berengere.lemen@onsemi.com,chris.gibson@onsemi.com

29. Account Manager Email: EHAAS@tsmc.com, GTHALLIKAR@tsmc.com, JXYHUANG@tsmc.com,  
LZENGA@tsmc.com, RWATERS@tsmc.com 30. Customer Support Email: ALEEA@tsmc.com 31. Customer Service  
Manager Email:

HHFAN@tsmc.com 32. CyberShuttle Captain Email: ZRHUANG [ZRHUANG@tsmc.com] 33. TSMC Remarks:


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IP Clarification: Please perform IP Clarification on TSMC-Online to prevent from using Problematic IP/Lib. (To perform IP  
Clarification, please access TSMC-Online > TapeOut & Mask Service > IP Clarification and follow the steps. After  
submitting the form, the IP Clarification report will be sent by email in 30 minutes. )

Sincerely yours,

TSMC CyberShuttle Team  
Zi-Ran Huang

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intended recipient. Any unauthorized review, use or distribution by anyone  
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immediately. Thank you.

 Répondre  Répondre à tous  Transférer    |   | Fermer  Aide

De: Christophe Pinatel

Date: jeu. 07/07/2011 14:29

À: Virginie Duchemann; Fabien Foulon; Patrice Delpy

Cc:

Objet : les remerciements de nos supérieurs US pour le projet NCP8381

Pièces jointes :

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**Pour votre info :**

**From:** Thibault Kassir

**Sent:** Wednesday, July 06, 2011 5:08 PM

**To:** Berengere Le Men; Eric Joseph

**Cc:** Stephen Dow; Radhika Venkatasubramanian; Adrian Lin; Brian Ballweber; David Lovelace; Martin Kejhar; Ling-Miao Chou; Josh Warner; Darren Hooks; Lang Dinh; Bob Boos; David McDonald; Bertrand Clou; Tim Gurnett; Philippe Andre; Dominique Romeo

**Subject:** Re: first evaluation results of the NCS8381

Excellent work! Thank you for the update and look forward to huge success \$\$ on this product.  
Thibault from BlackBerry

**From:** Josh Warner

**Sent:** Wednesday, July 06, 2011 5:07 PM

**To:** Berengere Le Men; Thibault Kassir; Eric Joseph

**Cc:** Stephen Dow; Radhika Venkatasubramanian; Adrian Lin; Brian Ballweber; David Lovelace; Martin Kejhar; Ling-Miao Chou; Darren Hooks; Lang Dinh; Bob Boos; David McDonald; Bertrand Clou; Tim Gurnett; Philippe Andre; Dominique Romeo

**Subject:** Re: first evaluation results of the NCS8381

This is excellent news, Berengere! Thank you to the entire design team for their hard work.

Looks like I have some traveling to do.

 Répondre  Répondre à tous  Transférer    Fermer  Aide

De: William Clemens  
À: Berengere Le Men; Alexandre Apcher; Virginie Duchemann; Fabien Foulon; Patrice Delpy  
Cc:  
Objet : RE: first evaluation results of the NCS8381  
Pièces jointes :

Date: ven. 08/07/2011 15:20

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Tout est dit ... Excellent !! Le weekend s'annonce bien J

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**William Clemens | Project Manager**

**ON Semiconductor France SA | 132, chemin de Basso Cambo - BP 53512 | 31035 Toulouse Cedex 1 | France**  
(: +33 534 61 1238 - )6: +33 534 61 1050 - \*: [william.clemens@onsemi.com](mailto:william.clemens@onsemi.com)

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**From:** Berengere Le Men  
**Sent:** Friday, July 08, 2011 2:44 PM  
**To:** Alexandre Apcher; Virginie Duchemann; Fabien Foulon; William Clemens; Patrice Delpy  
**Subject:** FW: first evaluation results of the NCS8381

Pour le plaisir J

**From:** Eric Joseph  
**Sent:** Thursday, July 07, 2011 7:21 PM  
**To:** Berengere Le Men  
**Cc:** Bertrand Clou  
**Subject:** RE: first evaluation results of the NCS8381

Great job Berengere. Please pass on my congratulations to the team.

Eric Joseph

VP, Design Engineering, CCPG

ON Semiconductor

1-602-244-5414

1-602-451-6110

**From:** Berengere Le Men

**Sent:** Wednesday, July 06, 2011 7:59 AM

**To:** Thibault Kassir; Eric Joseph

**Cc:** Stephen Dow; Radhika Venkatasubramanian; Adrian Lin; Brian Ballweber; David Lovelace; Martin Kejhar; Ling-Miao Chou; Josh Warner; Darren Hooks; Lang Dinh; Bob Boos; David McDonald; Bertrand Clou; Tim Gurnett; Philippe Andre; Dominique Romeo

**Subject:** first evaluation results of the NCS8381

Hello Thibault and Eric,

We just received the NCS8381 samples and we would like to share with you good news.

Indeed the preliminary evaluation shows good operating of the device. We did some audio listening of the amplifier in different modes and different power supplies with good responses at low and high power (full scale range) and in stereo. We did also some preliminary measurements on a first circuit with THD results in line with what expected (0.02% at 1kHz 8W 8Ohms and 16V). Noise measurements show results for now a little higher than expected (SNR=97dB instead of 100dB) but it's still very preliminary and investigation is ongoing. We tested also quickly functions like volume control, balance left and right, anti-clipping and DRC functions with good results. We tested different sample rates and different configurations which look ok.

The first results validate that the following blocks are functional:

- I2C/I2S interfaces
- Power tree (bias, 1.875V regulator and low noise buffer)
- 400MHz PLL
- Digital Signal Processing: Interpolation filters, PCM-PWM Modulator
- Digital audio enhancement: DRC, PGA, Balance, anti-clip
- PWM analog amplifier

These results are preliminary and need of course to be refined: the evaluation is pursuing. We keep you

posted.

If you want to enjoy the real life demo (audio), we will make it available soon under sharepoint project folder.

Best regards,

Berengere LE MEN, Philippe ANDRE, Dominique ROMEO